

Amendments to the CLAIMS

1. (currently amended) A dicing/die bonding adhesion tape comprising a substrate, a silicone adhesive layer directly on the substrate, which silicone adhesive layer is formed of a silicone adhesive composition comprising a heat curable chain-like organopolysiloxane and a solid silicone resin an organopolysiloxane copolymer resin composed of R¹₃SiO_{1/2} units and SiO₂ units wherein R¹ is a substituted or unsubstituted monovalent hydrocarbon radical and wherein the molar ratio of R¹₃SiO_{1/2} units to SiO₂ units is from 0.5 to 1.5 by heat curing, and a bonding layer directly on the silicone adhesive layer, wherein

the tack strength between the silicone adhesive layer and the bonding layer is 0.2 to 2.0 N/25 mm, and

said bonding layer is formed of an bonding composition comprising (A) a polyimide resin, (B) an epoxy resin, and (C) an epoxy resin curing catalyst.

2. (original) The adhesion tape of claim 1, wherein the substrate is an extensible film.

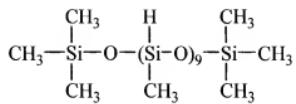
3. (original) The adhesion tape of claim 2, wherein the extensible film is polyethylene or polypropylene.

4. (previously presented) The adhesion tape of claim 1, wherein the silicone adhesive composition is an organic peroxide curing type or a platinum addition curing type silicone adhesive composition.

5. (original) The adhesion tape of claim 1, wherein the polyimide resin (A) in the bonding composition has phenolic hydroxyl radicals on its polymer skeleton.

6. (original) The adhesion tape of claim 1, wherein the polyimide resin (A) in the bonding composition has a siloxane structure in its polymer skeleton.

7. (previously presented) The adhesion tape of claim 1, wherein the silicone adhesive composition has the formula



8. (previously presented) The adhesion tape of claim 1, wherein the tack strength between the silicone adhesive layer and the bonding layer is 0.32 to 1.8 N/25 mm.

9. (previously presented) The adhesion tape of claim 1, wherein the bond strength ranges from 13 to 18 MPa.